

EPTC 2009

11th Electronics Packaging Technology Conference
9th - 11th December 2009 @ Shangri-La Hotel, Singapore

EPTC 2009 is a 3-day event and features technical sessions, short courses/forums, an exhibition, social and networking activities. It aims to provide good coverage of technological developments in all areas of electronic packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

We are privileged to have 4 Professional Development Courses, presented on Wednesday December 9th:

- **"Advanced Techniques for Microsystem Mechanical and Reliability Characterization,"** R. Gopal KRISHNAN / Sanjay Kumar THAKUR
- **"Advanced Cu Wirebonding Technology,"** Mohandass SIVAKUMAR / Hong Meng HO
- **"Advanced Thermal Management Techniques for Electronic Components,"** Avram BAR-COHEN, U-Maryland, USA
- **"Enabling Technologies for 3D IC Integration and WLP,"** John LAU, Hong Kong University of Science and Technology

The morning-session Workshop is **"Challenges and Opportunities of 3D Packaging"**

Workshop Chair is Dr. Charles BAUER. Topics:

"3D Packaging: Market Trends and Technology Drivers" - Dr. Vern SOLBERG

"Wafer Level Interconnection Technologies" - Prof. Rao TUMMALA

"Interposer and Substrate Technologies" - Dr. Bernd APPELT

"Thermal Management Solutions" - Prof. Avram BAR-COHEN

A panel discussion follows.

The EPTC also features a tabletop **exhibition** featuring suppliers of materials, equipment, components, software and service providers for the microelectronics and electronic assembly industries will be held during EPTC.

Register online at www.eptc-ieee.net

We are looking forward to seeing you at EPTC in Singapore!



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

Call for Papers
IEEE CPMT Symposium Japan
August 24 - 26, 2010
The University of Tokyo, Japan

The VLSI Packaging Workshop in Japan (vlsi-pkg-ws.org/vlsi-pkg.html) has been held biannually since 1992 in Kyoto, and it has become a well-known international workshop for advanced packaging technologies. Due to ever increasing activities and changing demands, the committee has reviewed its mission, cooperated with the members of IEEE CPMT Japan Chapter, refurbished the workshop, and started the new symposium—**IEEE CPMT Symposium Japan**. It will provide component, packaging, and manufacturing researchers who are extending their activities beyond borders with opportunities to exchange technical knowledge and perspective. The committee strongly encourages you to attend this symposium and participate in the discussion, to understand the technology trends and find the best targets for your technology/business development. Bring your latest research results and share with the participants who are experts from the industry and the grove of Academe, and discuss with them. Anybody contributing to the achievement of a sustainable society through electronics is very welcome at this symposium.

Important information

- Submission of abstract: **Feb. 15, 2010**
- Notification of acceptance: Mar. 31, 2010
- Submission of manuscript: May 15, 2010

Abstracts are requested in the following technical areas

- System in a Package (SiP)
- MEMS Packaging Technologies
- Advanced Fine Pitch Packaging
- Nano-Technology
- 3D Packaging & COC (Chip on Chip)
- Micro Bumping Technology
- Wafer Level CSP
- Electrical Performance & Thermal Management
- Packaging for Optoelectronics
- Failure Mechanisms & Reliability Improvement
- Packaging for Automobile
- Materials for High Speed Application & Wafer Process
- RF Components & Modules / RF Tags
- Green Material
- Integrated Passives / Embedded Components
- Assembly and Packaging Challenges for Cu/Low-k Chips
- Laminated Materials & Processing
- Emerging Technologies
- Board level reliability

Contact person

General Chair: Hirofumi Nakajima, NEC Electronics Co. (hirofumi.nakajima@necel.com)

Vice Chair: Hiroshi Yamada, Toshiba Co. (hiroshi.yamada@toshiba.co.jp)

Program Chair: Shigenori Aoki, Fujitsu Laboratories Ltd. (aoki.shigenori@jp.fujitsu.com)



Advanced Packaging Materials Conference (APM) *(Incorporating Polytronic)* & MicroTech-2010

28th February – 2nd March 2010

Cambridge, England

First Call for Abstracts - Submission Deadline: 30th November 2009

EVENT

The IEEE-CPMT Advanced Packaging Materials (AMP) and IMAPS-UK MicroTech-2010 will be the major Spring 2010 event on Electronics packaging, interconnection and integration conference in Europe.

AMP featuring advanced polymer, organic and inorganic materials & MicroTech-2010 featuring Disruptive Technologies will be held at the well known University of Cambridge Møller Centre. The location is ideally placed near many of the forward thrusting new and established companies as well as at a great historic city.

The conference will feature Keynote talks, technical presentations, and exhibits, that provide leading-edge coverage of developments in all areas of packaging materials and processes. Attendees in the past have included academic researchers, developers, producers, and users of packaging materials from all over the world. APM, Polytronic and MicroTech are also major packaging materials forums, providing opportunities to network and meet leading experts and exchange up-to-date packaging knowledge in the field.

Abstract and Paper Requirements

Authors from industry and academia with innovative research or developments are invited to submit Abstracts for this forthcoming major international Conference. Abstracts must be between 250 and 500 words and must include results and graphics. Papers from industry are especially important. Such papers will necessarily have product content. However, commercially orientated material and descriptions are not permitted either in the paper or in the presentation or poster. Authors will also benefit from the opportunity for papers to be selected from the Conference Proceedings for publication in IMAPS iKnow and IEEE Xplore.

Technical Topics:

Disruptive Technologies • Advanced Packaging • Polymeric Materials • Inorganic Materials • Emerging Technologies • Manufacturing and Test Technology • Modelling, Simulation and Design • New Materials and Processes • Materials for Thermal Management • Reliability • LED'S, OLED's and optical packaging materials • Nano & Bio Materials • Adhesives • RoHS Compliant Materials

Poster papers will be on display throughout the days and each poster will have a scheduled slot for presentation by the author.

Short Courses:

Half day short courses will take place on the Sunday 28th February. Proposals for short-course Master Classes are also invited.

Technical Contacts: Nihal Sinnadurai (sinnadurai@aol.com) or Chris Bailey (C.Bailey@gre.ac.uk)

Submit Abstracts at the website apm-microtech.gre.ac.uk/

Exhibition

A tabletop exhibition featuring suppliers of materials, equipment, components, software, and services to the electronics industry will be held at the event

Accommodation

The Møller Centre (www.mollercentre.co.uk/location/index.html)

Conference Secretariat: Vicky Holland (IMAPSUK@aol.com)

Conference Co-Chairs:

Nihal Sinnadurai

Chair IEEE-CPMT (UK&RI)

APM-2010

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CALL FOR PAPERS -- Abstracts due February 1, 2010



JOIN US IN BERLIN FOR THE THIRD ELECTRONICS SYSTEM INTEGRATION TECHNOLOGY CONFERENCE!

ESTC 2010 will bring you up to date on the latest international developments in microsystem technology and electronic packaging. It will feature a powerful technical program, as well as professional short courses on state-of-the-art technologies. On more than 750 m² exhibition area companies and research institutions will present new products and services.

Technological Topics

- Advanced packaging
- Microsystem packaging
- New materials and processes
- Optoelectronics
- Assembly and manufacturing technology
- Modelling and simulation
- Applied reliability
- Power electronics
- Electrical design and modelling
- Emerging technologies

For further information please go to <http://www.estc-2010.de>

**IEEE Components, Packaging and Manufacturing
Technology Society**

Marsha Tickman, Executive Director
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Visit our website

www.cpmt.org

Download the PDF version of this NEWSLETTER,
to circulate to other professionals

www.cpmt.org/newsletter/

2009/2010 Deadlines for Submitting Articles:

November 25th, 2009 February 25th, 2010

May 25th, 2010 August 25th, 2010

Only Articles sent to nsltr-input@cpmt.org

will be included in the newsletter

Members-only Web (www.cpmt.org/mem/)

UserName: [available to Members --

Password: join CPMT!]

14th IEEE Workshop On

CALL FOR PAPERS (SPI 2010)

SIGNAL PROPAGATION ON INTERCONNECTS

Sponsored by the IEEE Computer Society – Test Technology Technical Council (TTTC) and
by the IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society

May 09-12, 2010 - “Van der Valk Hotel” - Hildesheim, Germany

SPI has developed into a forum for exchange of the latest research results in this area. The is to report on the most recent developments in the field of interconnect modeling, simulation and measurement on chips, boards, and packages. The event is also meant to bring together developers and researchers from industry and academia in order to encourage cooperation. The workshop will be held in English. Detailed information about the workshop and its location are available on the website.

Main topics of the workshop include, but not limited to:

- Frequency Domain Measurement Techniques
- Time Domain Measurement Techniques
- Modeling of Package & On-Chip Interconnects
- Macromodeling - Testing & Interconnects
- Substrate Effects - Power/Ground-Noise
- Optical Interconnects - Wireless Interconnects
- Simulation Techniques for Interconnect Structures
- Electromagnetic Field Theory
- Analysis & Modeling of Power Distribution Networks
- Propagation Characteristics on Transmission Lines
- Coupling Effects on Interconnects
- Guided Waves on Interconnects
- Radiation & Interference
- Electromagnetic Compatibility
- RF and Microwave Interconnects

SUBMISSION OF ABSTRACTS:

Those who wish to contribute to the workshop should send (by eMail only) a formatted two- to four-page paper to the Program Chair by **January 29, 2010**. If the paper is accepted, it will be reproduced, as is, in the workshop proceedings. Notification about acceptance will be given by March 31, 2010.

For submission instructions see “Author’s Kit” on our website:

www.spi.uni-hannover.de

PROGRAM-CHAIR: Uwe Arz, Physikalisch-Technische Bundesanstalt, Arbeitsgruppe 2.23, On-Wafer-Mikrowellenmesstechnik, Bundesallee 100, 38116 Braunschweig (Germany) – Phone: +49 531 592 2297; Fax: +49 531 592 2228; uwe.arz@ptb.de

**We are looking forward to
seeing you in Hildesheim!**